



# Material Composition Declaration

## EPC23102

Company Name	Efficient Power Conversion (EPC)	Issue Date:	8/11/2025
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	35.1 mg	Type of Product:	eGaN FET in FCQFN package

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)		
Chip	Silicon	7440-21-3	10.1436	28.9391	30.5578	289391
	Silicon oxide	7631-86-9	0.1103	0.3147		3147
	Silicon nitride	12033-89-5	0.0313	0.0894		894
	Gallium nitride	25617-97-4	0.0661	0.1886		1886
	Aluminum	7429-90-5	0.1184	0.3379		3379
	Aluminum nitride	24304-00-5	0.0146	0.0417		417
	Titanium	7440-32-6	0.0029	0.0083		83
	Titanium nitride	25583-20-4	0.0604	0.1722		1722
	Copper	7440-50-8	0.0020	0.0056		56
	Tungsten	7440-33-7	0.0059	0.0168		168
	Polyimide		0.1554	0.4434		4434
Under Bump Metal	Titanium	7440-32-6	0.0005	0.0015	0.0161	15
	Copper	7440-50-8	0.0051	0.0146		146
Internal Solder Bump	Copper	7440-50-8	0.4309	1.2294	1.6798	12294
	Nickel	7440-02-0	0.0306	0.0873		873
	Tin	7440-31-5	0.1250	0.3566		3566
	Silver	7440-22-4	0.0023	0.0065		65
Package	Copper	7440-50-8	13.0938	37.3558	67.7463	373558
	Iron	7439-89-6	0.3357	0.9578		9578
	Mold Compound		9.6733	27.5973		275973
External pins Coating	Tin	7440-31-5	0.6433	1.8352		18352
Sum in total:			35.0515	100.0000	100.0000	1000000

**Note:**

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.